

## CL74LVC2G17 Dual Schmitt-Trigger Buffer

### General Description

This dual Schmitt-Trigger buffer is designed for 1.65-V to 5.5-V VCC operation.

The CL74LVC2G17 device contains two buffers and performs the Boolean function  $Y = A$ . The device functions as two independent buffers, but because of Schmitt action, it may have different input threshold levels for positive-going ( $V_{T+}$ ) and negative-going ( $V_{T-}$ ) signals.

This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

### Ordering Information

Part Number	Package	
CL74LVC2G17	SOT-23- SOT-25 SOT-353 SOT-553	

### Features

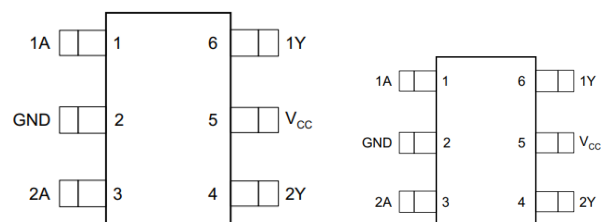
- Schmitt-Trigger inputs provide hysteresis
- Supports 5-V Vcc operation
- Inputs Accept Voltages to 5.5 V
- Max Tpd of 5.4 ns at 3.3 V
- Low Power Consumption, 10- $\mu$ A Max  $I_{cc}$
- $\pm 24$ -mA Output Drive at 3.3 V
- Typical  $V_{OLP}$ (Output Ground Bounce) $<0.8$ V at  $V_{CC} = 3.3$ V,  $T_A = 25^\circ\text{C}$
- Typical  $V_{OHV}$ (Output  $V_{OH}$  Undershoot) $>2$ V at  $V_{CC} = 3.3$ V,  $T_A = 25^\circ\text{C}$
- $I_{off}$  Supports Live Insertion, Patial-Power-Down Mode, and Back-Drive Protection

- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 1000-V Charged-Device Model (C101)

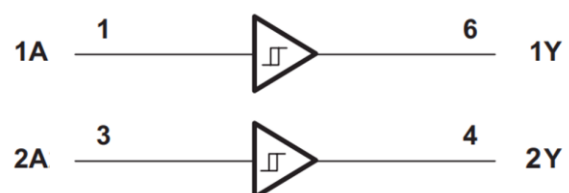
### Applications

- AV Receiver
- Audio Dock: Portable
- Blu-ray Player and Home Theater
- MP3 Player/Recorder (Portable Audio)
- Personal Digital Assistant (PDA)
- Power: Telecom/Server AC/DC Supply: Single Controller: Analog and Digital
- Solid State Drive (SSD): Client and Enterprise
- TVs: LCD/Digital and High-Definition (HDTV)
- Tablet: Enterprise
- Video Analytics: Server
- Wireless Headset, Keyboard, and Mice

### Pin Configuration



### Simplified Schematic





## Pin Assignment

# CL74LVC2G17

Pin Name	Pin No.	Pin Function
GND	2	Ground
1A	1	Input 1
2A	3	Input 2
1Y	6	Open-drain output 1
2Y	4	Open-drain output 2
Vcc	5	Power pin

### Absolute Maximum Ratings (Note1)

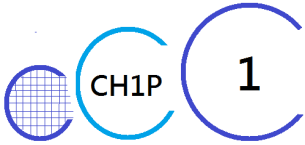
- $V_{CC}$  ----- -0.5V to +6.5V
- $V_I$ ----- -0.5V to +6.5V
- $V_O$ (Voltage range applied to any output in the high-impedance or power-off state)----- -0.5V to +6.5V
- $V_O$ (Voltage range applied to any output in the high or slow state)----- -0.5V to  $V_{CC}+0.5V$
- Input clamp current ----- -50mA
- Output clamp current ----- -50mA
- Continuous output current -----  $\pm 50mA$
- Storage Temperature -----  $-65^{\circ}C$  to  $150^{\circ}C$

### Recommended Operating Conditions

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Supply voltage	$V_{CC}$	Operating	1.65		5.5	V
Input voltage	$V_I$		0		5.5	V
Output voltage	$V_O$		0		VCC	V
High- level output current	$I_{OH}$	$V_{CC} = 1.65V$			-4	mA
		$V_{CC} = 2.3V$			-8	
		$V_{CC} = 3V$			-16	
		$V_{CC} = 3V$			-24	
		$V_{CC} = 4.5V$			-32	
Low- level output current	$I_{OL}$	$V_{CC} = 1.65V$			4	mA
		$V_{CC} = 2.3V$			8	
		$V_{CC} = 3V$			16	
		$V_{CC} = 3V$			24	
		$V_{CC} = 4.5V$			32	
Operating temperature	$T_A$		-40		125	$^{\circ}C$

## Electrical Characteristics

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Positive-going input threshold voltage	$V_{T+}$	$V_{CC} = 1.65V$	0.7		1.4	V
		$V_{CC} = 2.3V$	1.0		1.7	
		$V_{CC} = 3V$	1.3		2.0	
		$V_{CC} = 4.5V$	1.9		3.1	
		$V_{CC} = 5.5V$	2.2		3.7	
Negative-going input threshold voltage	$V_{T-}$	$V_{CC} = 1.65V$	0.3		0.7	V
		$V_{CC} = 2.3V$	0.4		1	
		$V_{CC} = 3V$	0.8		1.3	
		$V_{CC} = 4.5V$	1.1		2	
		$V_{CC} = 5.5V$	1.4		2.5	
Hysteresis voltage	$\Delta V_T$	$V_{CC} = 1.65V$	0.3		0.8	V
		$V_{CC} = 2.3V$	0.4		0.9	
		$V_{CC} = 3V$	0.4		1.1	
		$V_{CC} = 4.5V$	0.6		1.3	
		$V_{CC} = 5.5V$	0.7		1.4	
High- level output voltage	$V_{OH}$	$V_{CC} = 1.65 \sim 5.5V, I_{OH} = 100\mu A$	$V_{CC} - 0.1$			V
		$V_{CC} = 1.65V, I_{OH} = 4mA$	1.2			
		$V_{CC} = 2.3V, I_{OH} = 8mA$	1.9			
		$V_{CC} = 3V, I_{OH} = 16mA$	2.4			
		$V_{CC} = 3V, I_{OH} = 24mA$	2.3			
		$V_{CC} = 4.5V, I_{OH} = 32mA$	3.8			
Low- level output voltage	$V_{OL}$	$V_{CC} = 1.65 \sim 5.5V, I_{OL} = 100\mu A$			0.1	V
		$V_{CC} = 1.65V, I_{OL} = 4mA$			0.45	
		$V_{CC} = 2.3V, I_{OL} = 8mA$			0.3	
		$V_{CC} = 3V, I_{OL} = 16mA$			0.4	
		$V_{CC} = 3V, I_{OL} = 24mA$			0.55	
		$V_{CC} = 4.5V, I_{OL} = 32mA$			0.55	
Input leakage current	$I_I$	$V_{IN} = 5.5V$ or GND, $V_{CC} = 0 \sim 5.5V$			$\pm 5$	$\mu A$
Power off leakage current	$I_{OFF}$	$V_I$ or $V_O = 5.5V, V_{CC} = 0V$			$\pm 10$	$\mu A$
Supply current	$I_{CC}$	$V_{IN} = V_{CC}$ or GND, $I_{OUT} = 0, V_{CC} = 1.65 \sim 5.5V$			10	$\mu A$
Additional supply current per input pin	$\Delta I_{CC}$	$V_{CC} = 3 \sim 5.5V$ , one input at $V_{CC} - 0.6V$ , other input at $V_{CC}$ or GND			500	$\mu A$

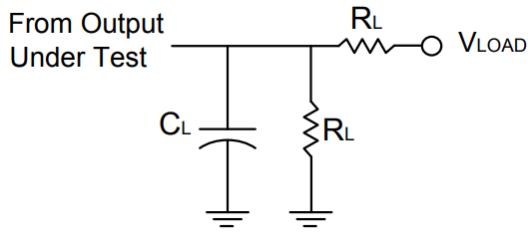


# CL74LVC2G17

## Switching Characteristics

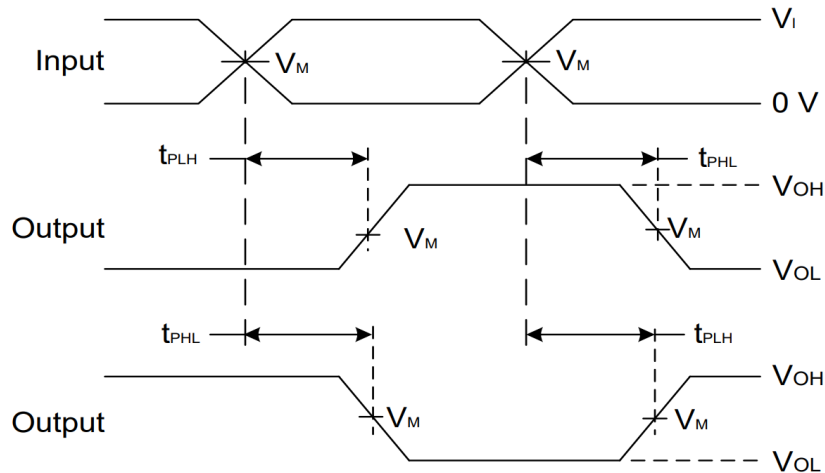
Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Propagation delay from input(A or B) to output(Y)	$T_{PD}$	$V_{CC} = 1.8V \pm 0.15V, R_L = 1K\Omega$	3.9		9.3	ns
		$V_{CC} = 2.5V \pm 0.2V, R_L = 500\Omega$	1.9		5.7	
		$V_{CC} = 3.3V \pm 0.3V, R_L = 500\Omega$	2.2		5.4	
		$V_{CC} = 5V \pm 0.5V, R_L = 500\Omega$	1.5		4.3	

## Parameter Measurement Information



TEST	Condition
$t_{PLZ}$	$V_{LOAD}$
$t_{PZL}$	$V_{LOAD}$

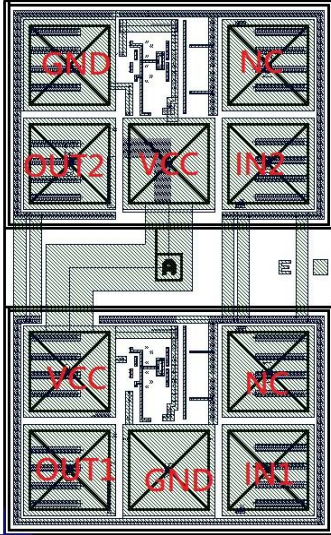
VCC	INPUTS		$V_M$	$V_{LOAD}$	$C_L$	$R_L$	$V_{\Delta}$
	$V_I$	$t_r/t_f$					
$1.8V \pm 0.15V$	$V_{CC}$	$\leq 2ns$	$V_{CC}/2$	$2 \times V_{CC}$	30pF	1k $\Omega$	0.15V
$2.5V \pm 0.2V$	$V_{CC}$	$\leq 2ns$	$V_{CC}/2$	$2 \times V_{CC}$	30pF	500 $\Omega$	0.15V
$3.3V \pm 0.3V$	3V	$\leq 2.5ns$	1.5V	6V	50pF	500 $\Omega$	0.3V
$5V \pm 0.5V$	$V_{CC}$	$\leq 2.5ns$	$V_{CC}/2$	$2 \times V_{CC}$	50pF	500 $\Omega$	0.3V



**Voltage Waveform Propagation Delay Times  
Inverting and Non Inverting Outputs**

- Notes:
- A.  $C_L$  includes probe and jig capacitance
  - B. All pulses and supplied at pulse repetition rate  $\leq 10MHz$
  - C. The Inputs are measured separately one transition per measurement
  - D.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{PD}$

## PAD Location and Coordinates

PHYSICAL CHARACTERISTICS		UNIT	CHIP DRAWING
Wafer Size	200	mm	
Die Size (with S/L)	0.308 * 0.466	mm <sup>2</sup>	
Scribe line width	60	um	
TOP Metal thickness	3	um	
Top Metallization	Al-Cu		
Wafer Thickness	726	um	
CUP (circuit under PAD) or not	YES		
Bonding Wire Diameter	20	um	

PAD NAME	PAD SIZE (μm <sup>2</sup> )	Coordinate
IN2	60*60	(199,282)
GND	60*60	(49,357)
GND	60*60	(124,49)
IN1	60*60	(199,49)
OUT1	60*60	(49,49)
VCC	60*60	(49,124)
OUT2	60*60	(49,282)

Bonding Diagram Example

